## Product / Package Information

| | |
|---|---|
| **Package** | LFCSP - Sawn |
| **Body Size (mm)** | 5 X 5 X 0.75 (3.3 EP) |
| **Lead Count** | 28 |
| **Terminal Finish** | 100 Sn |

## Environmental Information

| | |
|---|---|
| **RoHS Compliant** | Yes |
| **High Temperature Compliant** | Yes |
| **Halogen Free Compliant** | Yes |
| **REACH SVHC Compliant** | Yes |

## Materials Declaration

### Molding Compound

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other inorganic materials | Silica | 60676-86-0 | 3.53E-02 | 86.2 | 862000 | 38.41 | 384129 |
| Thermosets | Epoxy resin | Proprietary | 2.45E-03 | 6.0 | 60000 | 2.67 | 26737 |
| Thermosets | Phenol resin | Proprietary | 2.45E-03 | 6.0 | 60000 | 2.67 | 26737 |
| Other inorganic materials | Metal Hydroxide | Proprietary | 6.14E-04 | 1.5 | 15000 | 0.67 | 6684 |
| Other inorganic materials | Carbon black | 1333-86-4 | 1.23E-04 | 0.3 | 3000 | 0.13 | 1337 |
| Subtotal | | | 4.09 E-02 | 100.00 | 1000000 | 44.56 | 445625 |

### Leadframe

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Copper & its alloys | Copper | 7440-50-8 | 4.34 E-02 | 97.50 | 975000 | 47.27 | 472727 |
| Copper & its alloys | Iron | 7439-89-6 | 1.05 E-03 | 2.35 | 23500 | 1.14 | 11394 |
| Copper & its alloys | Zinc | 7440-66-6 | 5.34 E-05 | 0.12 | 1200 | 0.06 | 582 |
| Copper & its alloys | Phosphorus | 7723-14-0 | 1.34 E-05 | 0.03 | 300 | 0.01 | 145 |
| Subtotal | | | 4.45 E-02 | 100.00 | 1000000 | 48.48 | 484848 |

### Internal Leadframe Plating

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious metals | Silver | 7440-22-4 | 1.11 E-04 | 100.0 | 1000000 | 0.12 | 1212 |

### External Leadframe Plating

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Tin & its alloys | Tin | 7440-31-5 | 2.10 E-03 | 100.0 | 1000000 | 2.29 | 22880 |

### Bond Wires

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious metals | Gold | 7440-57-5 | 3.20 E-04 | 100.0 | 1000000 | 0.35 | 3487 |

### Chip

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Other inorganic materials | Doped Silicon | 7440-21-3 | 3.30 E-03 | 100.0 | 1000000 | 3.60 | 35955 |

### Die Attach

| Description | Substance | CAS# | Weight (g) | Homogeneous Material Level | | Component Level | |
|---|---|---|---|---|---|---|---|
| | | | | Percentage (%) | PPM | Percentage (%) | PPM |
| Precious metals | Silver | 7440-22-4 | 4.04 E-04 | 73.54 | 735400 | 0.44 | 4407 |
| Other organic materials | Epoxy resin A | TS ref# 10013 | 4.04 E-05 | 7.35 | 73500 | 0.04 | 440 |
| Others | Anhydride | TS ref# 10181 | 4.04 E-05 | 7.35 | 73500 | 0.04 | 440 |
| Other organic materials | 2,6-Diglycidyl phenyl allyl ether oligomer | Unassigned | 1.62 E-05 | 2.94 | 29400 | 0.02 | 176 |
| Other organic materials | Epoxy resin B | TS ref# 10237 | 1.62 E-05 | 2.94 | 29400 | 0.02 | 176 |
| Others | Epoxy resin modifier | TS ref# 10038 | 1.62 E-05 | 2.94 | 29400 | 0.02 | 176 |
| Others | Anhydride | TS ref# 10180 | 1.62 E-05 | 2.94 | 29400 | 0.02 | 176 |
| Subtotal | | | 5.50 E-04 | 100.0 | 1000000 | 0.60 | 5993 |

| | Weight (g) | Percentage (%) | PPM |
|---|---|---|---|
| **Package Totals** | **9.18 E-02** | **100** | **1000000** |

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.